



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

KONISHI et al. Atty. Ref.: 829-615; Confirmation No.

Appl. No. 10/659,261 TC/A.U. 1722

Filed: September 11, 2003 Examiner: Davis, Robert B.

For: RESIN MOLDING DIE AND PRODUCTION METHOD FOR SEMICONDUCTOR
DEVICES USING THE SAME

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August 30, 2005

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT

Responsive to the Official Action dated May 4, 2005 (for which petition is hereby made
for a one month extension of time), please amend the above-identified application as follows:

08/31/2005 JADDO1 00000141 10659261
01 FC:1251 120.00 0P